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Jameco Part Number 1762728

# Surface Mount Varistors

## Multilayer High Speed Transient Voltage Surge Suppressor

### **RoHS** MHS Varistor Series

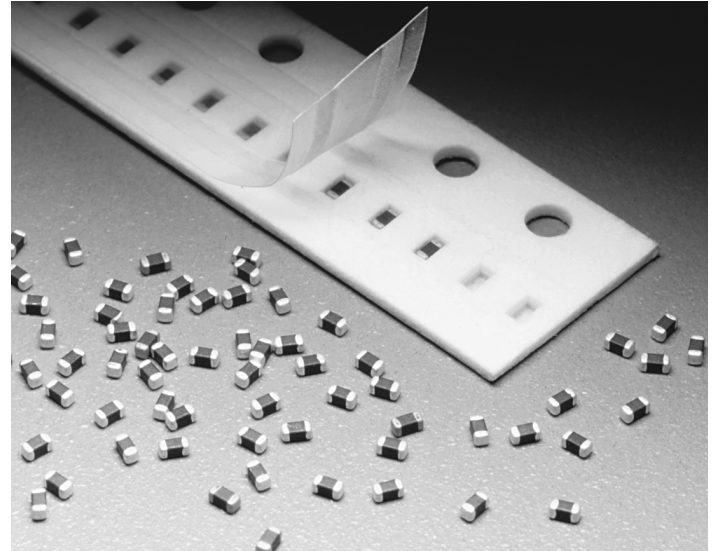
The Multilayer High-Speed MHS Series is a very-low capacitance extension to the Littelfuse ML family of Transient Voltage Surge Suppression devices available in an 0402 and 0603-size surface mount chip.

The MHS series provides protection from ESD and EFT in high-speed data-line and other high frequency applications. The low capacitance of the MHS Series permits usage in analog or digital circuits where it will not attenuate or distort the desired signal or data.

Their small size is ideal for high-density printed circuit boards, being typically applied to protect intergrated circuits and other sensitive components. They are particularly well suited to suppress ESD events including those specified in IEC 61000-4-2 or other standards used for ElectroMagnetic Compliance (EMC) testing.

The MHS series is manufactured from semiconducting ceramics and is supplied in a leadless, surface mount package. The MHS Series is also compatible with modern reflow and wave soldering processes.

Littelfuse Inc. manufactures other Multilayer Varistor Series products, see the ML, MLE, MLN and AUML series data sheets.



### Features

- RoHS Compliant
- 3pF, 12pF, and 22pF Capacitance Versions Suitable for High Speed Data-Rate Lines
- ESD Rated to IEC 61000-4-2 (Level 4)
- EFT/B Rated to IEC 61000-4-4 (Level 4)
- Low Leakage Currents
- -55°C to +125°C Operating Temperature Range
- Inherently Bi-directional

### Applications

- Data, Diagnostic I/O Ports
- Universal Serial Bus (USB)
- Video & Audio Ports
- Portable/Hand-Held Products
- Mobile Communications
- Computer/DSP Products
- Industrial Instruments Including Medical

### Size

Metric	EIA
1005	0402
1608	0603

3  
SURFACE MOUNT  
VARISTORS

**Absolute Maximum Ratings** For ratings of individual members of a series, see device ratings and specifications table.

**MHS SERIES      UNITS**

Continuous:

Steady State Applied Voltage: DC Voltage Range ( $V_{M(DC)}$ ):	V0402/0603MHS03	≤ 42	V
	V0402/0603MHS12	≤ 18	V
	V0402/0603MHS22	≤ 9	V
Operating Ambient Temperature Range ( $T_A$ )		-55 to + 125	°C
Storage Temperature Range ( $T_{STG}$ )		-55 to + 150	°C

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### Device Ratings and Specifications

PART NUMBER	MAX RATINGS (125°C)	PERFORMANCE SPECIFICATIONS (25°C)						
	MAXIMUM NON-REPETITIVE SURGE ENERGY (10/1000μs) $W_{TM}$	MAXIMUM CLAMPING VOLTAGE AT 1A (8X20μs) (Vc)	MAXIMUM ESD CLAMP VOLTAGE (NOTE 1)		TYPICAL LEAKAGE CURRENT AT SPECIFIED DC VOLTAGE		TYPICAL CAPACITANCE AT 1MHz (1V p-p) (NOTE 4) C	TYPICAL INDUCTANCE (from Impedance Analysis) L
			(Note 2) 8kV CONTACT Clamp	(Note 3) 15kV AIR Clamp	3.5V P	5.5V I <sub>L</sub>		
(J)	(V)	(V)	(V)	(μA)	(μA)	(pF)	(nH)	
V0402MHS03 V0603MHS03	0.050 0.010	135 135	<300 <300	<400 <400	0.5 0.5	1.00 1.00	3 3	<1.0 <1.0
V0402MHS12 V0603MHS12	0.100 0.025	55 55	<125 <125	<160 <160	0.5 0.5	1.00 1.00	12 12	<1.0 <1.0
V0402MHS22 V0603MHS22	0.100 0.020	30 30	<125 <65	<160 <100	0.5 0.5	1.00 1.00	22 22	<1.0 <1.0

NOTES:

1. Tested to IEC-61000-4-2 Human Body Model (HBM) discharge test circuit.
2. Direct discharge to device terminals (IEC preferred test method).
3. Corona discharge through air (represents actual ESD event).
4. Capacitance may be customized, contact your Littelfuse Sales Representative.

### Temperature De-rating

For applications exceeding 125°C ambient temperature, the peak surge current and energy ratings must be reduced as shown in Figure 1.

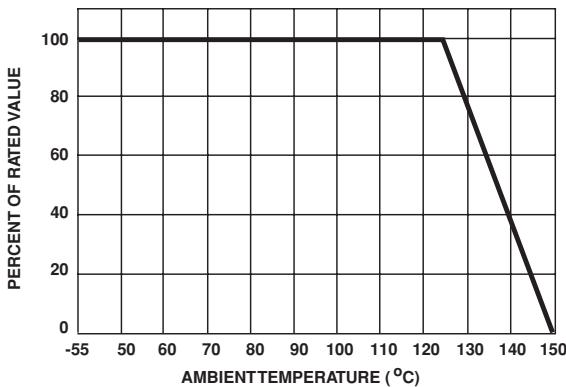


FIGURE 1. PEAK CURRENT AND ENERGY DERATING CURVE

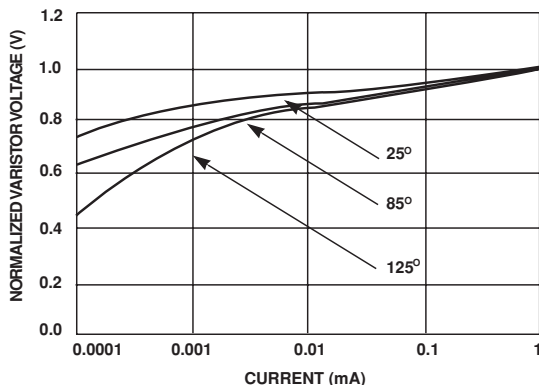


FIGURE 2. STANDBY CURRENT AT NORMALIZED VARISTOR VOLTAGE AND TEMPERATURE

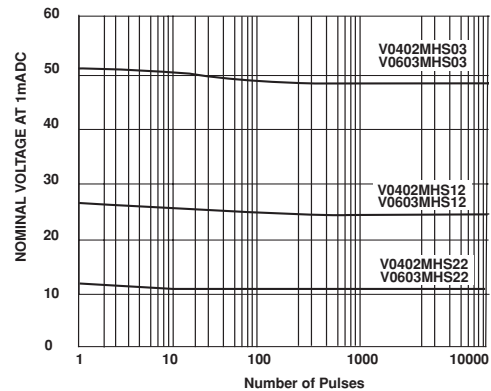


FIGURE 3. NOMINAL VOLTAGE STABILITY TO MULTIPLE ESD IMPULSES (8KV CONTACT DISCHARGES PER IEC 61000-4-2)

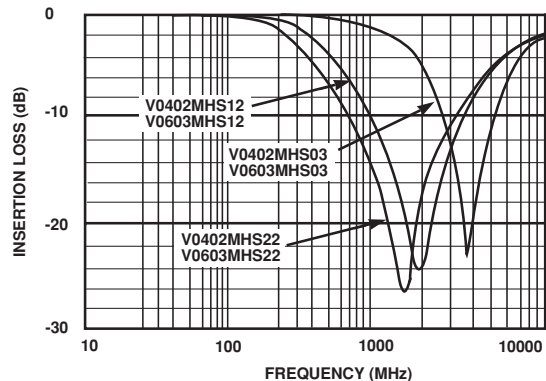


FIGURE 4. INSERTION LOSS (S21) CHARACTERISTICS

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#### Soldering Recommendations

##### Lead (Pb) Soldering Recommendations

The principal techniques used for the soldering of components in surface mount technology are IR Re-flow & Wave soldering. Typical profiles are shown in Figures 5 & 6.

The recommended solder for the ML suppressor is a 62/36/2 (Sn/Pb/Ag), 60/40 (Sn/Pb) or 63/37 (Sn/Pb). Littelfuse also recommends an RMA solder flux.

Wave soldering is the most strenuous of the processes. To avoid the possibility of generating stresses due to thermal shock, a preheat stage in the soldering process is recommended, and the peak temperature of the solder process should be rigidly controlled.

When using a reflow process, care should be taken to ensure that the ML chip is not subjected to a thermal gradient steeper than 4 degrees per second; the ideal gradient being 2 degrees per second. During the soldering process, preheating to within 100 degrees of the solder's peak temperature is essential to minimize thermal shock.

Once the soldering process has been completed, it is still necessary to ensure that any further thermal shocks are avoided. One possible cause of thermal shock is hot printed circuit boards being removed from the solder process and subjected to cleaning solvents at room temperature. The boards must be allowed to cool gradually to less than 50°C before cleaning.

##### Lead-free (Pb-free) Soldering Recommendations

Littelfuse offers the Nickel-Barrier termination finish for the optimum Pb-free solder performance.

The preferred solder is 96.5/3.0/0.5 (SnAgCu) with an RMA flux, but there is a wide selection of pastes & fluxes available with which the nickel barrier parts should be compatible.

The reflow profile must be constrained by maximums shown in Figure 7. For Pb-free Wave soldering, Figure 6 still applies.

Note: the Pb-free paste, flux & profile were used for evaluation purposes by Littelfuse, based upon industry standards & practices. There are multiple choices of all three available, it is advised that the customer explores the optimum combination for their process as processes vary considerably from site to site.

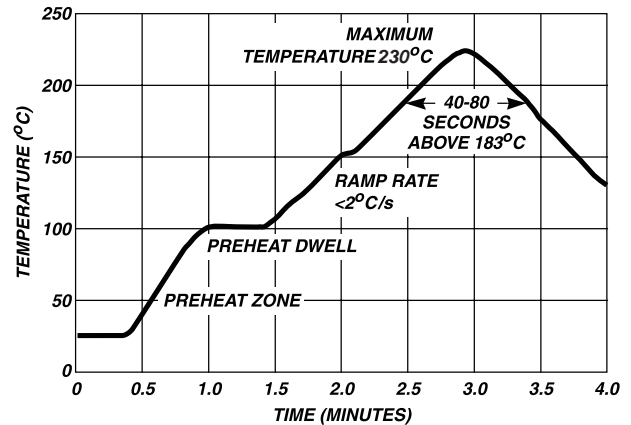


FIGURE 5. REFLOW SOLDER PROFILE

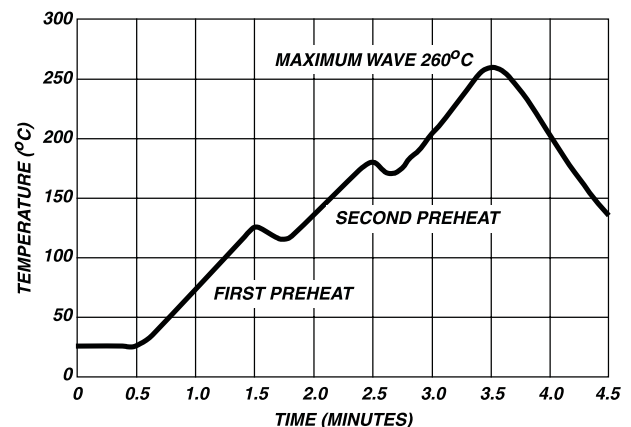


FIGURE 6. WAVE SOLDER PROFILE

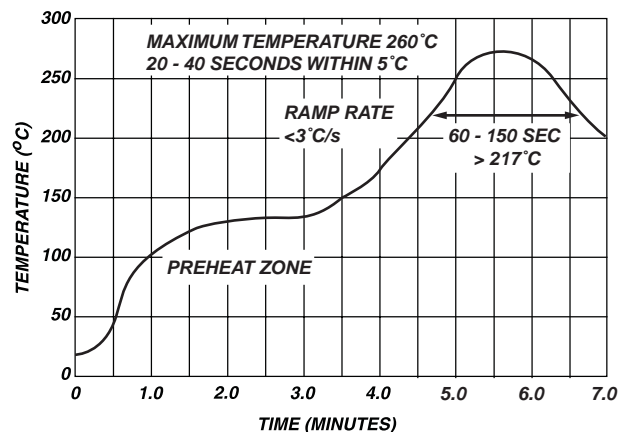


FIGURE 7. LEAD-FREE RE-FLOW PROFILE

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#### Multilayer High Speed - MHS Series

##### Recommended Pad Outline

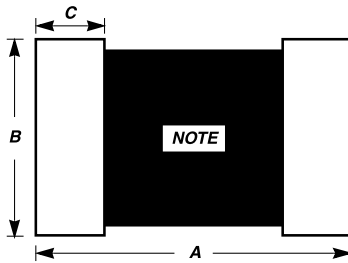
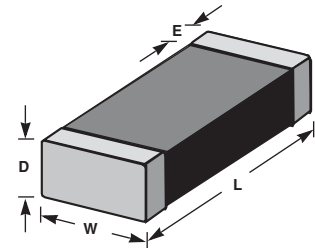


TABLE 1: PAD LAYOUT DIMENSIONS

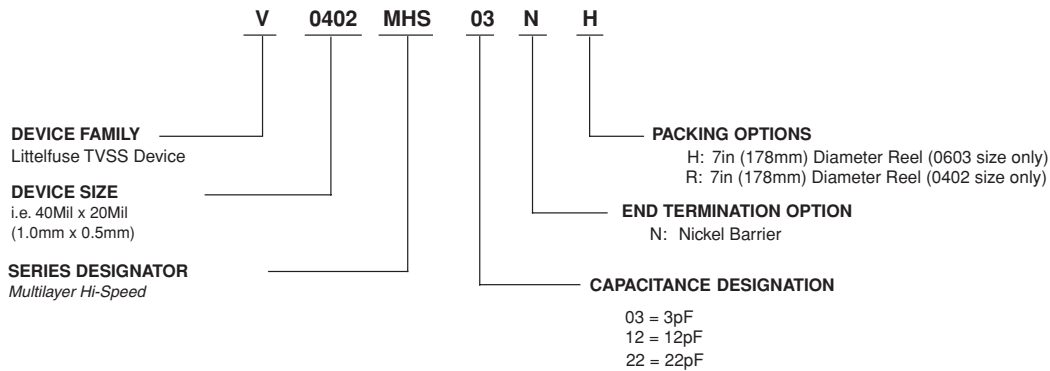
DIMENSION	A		B		C	
	mm	in	mm	in	mm	in
0402	1.70	0.067	0.510	0.020	0.610	0.024
0603	2.54	0.100	0.760	0.030	0.890	0.035

##### Mechanical Dimensions



DIMENSION	DEVICE DIMENSIONS			
	0402 SIZE		0603 SIZE	
	INCH	MM	INCH	MM
<b>D Max.</b>	0.024	0.60	0.035	0.9
<b>E</b>	0.10±0.006	0.25±0.15	0.015±0.008	0.4±0.2
<b>L</b>	0.039±0.004	1.00±0.10	0.063±0.006	1.6±0.15
<b>W</b>	0.020±0.004	0.50±0.10	0.032±0.006	0.8±0.15

#### Ordering Information



#### Standard Shipping Quantities

SIZE	7 INCH REEL ("H" OPTION)	13 IN REEL "T" OPTION
0402	10,000	50,000
0603	2,500	10,000

**RoHS MHS Varistor Series**

**Multilayer High Speed - MHS Series**

**Tape and Reel Specifications**

- Conforms to EIA-481-1, Revision A
- Can be supplied to IEC publication 286-3

SYMBOL	DESCRIPTION	DIMENSIONS IN MILLIMETERS	
		0402 Size	0603 Size
A <sub>0</sub>	Width of Cavity	Dependent on Chip Size to Minimize Rotation.	
B <sub>0</sub>	Length of Cavity	Dependent on Chip Size to Minimize Rotation.	
K <sub>0</sub>	Depth of Cavity	Dependent on Chip Size to Minimize Rotation.	
W	Width of Tape	8±0.2	
F	Distance Between Drive Hole Centers and Cavity Centers	3.5±.05	
E	Distance Between Drive Hole Centers and Tape Edge	1.75±0.1	
P <sub>1</sub>	Distance Between Cavity Centers	2±0.05	4±0.1
P <sub>2</sub>	Axial Drive Distance Between Drive Hole Centers & Cavity Centers	2±0.1	
P <sub>0</sub>	Axial Drive Distance Between Drive Hole Centers	4±0.1	
D <sub>0</sub>	Drive Hole Diameter	1.55±0.05	
D <sub>1</sub>	Diameter of Cavity Piercing	N/A	1.05±0.05
T <sub>1</sub>	Top Tape Thickness	0.1 Max	
T	Nominal Carrier Tape Thickness	0.61	1.1

